SUMMARY

PROBLEMS TO BE SOLVED

[0006]

In view of such situations, an object of the embodiments disclosed herein is to provide an adhesive composition which allows an alignment mark to be recognized, ensures sufficient solder wettability of a joining section, and is excellent in suppression of void generation.

SOLUTIONS TO THE PROBLEMS

[0007]

That is, in an aspect, there is provided an adhesive composition including: a high-molecular compound (A); an epoxy compound (B) having a weight average molecular weight of 100 or more and 3,000 or less; and a flux (C); and inorganic particles (D) which have on the surfaces thereof an alkoxysilane having a phenyl group and which have an average particle diameter of 30 to 200 nm, the flux (C) containing an acid-modified rosin.

[0007a]

In another aspect, there is provided a semiconductor device comprising a cured product of the adhesive composition as defined above.

[0007b]

In another aspect, there is provided a method for manufacturing a semiconductor device, the method comprising interposing the adhesive composition as defined above between a first circuit member and a second circuit member, and electrically connecting the first circuit member and the second circuit member.

EFFECTS

[0008]

According to the present disclosure, there can be provided an adhesive composition which allows an alignment mark to be recognized, ensures sufficient solder wettability of a joining